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(12) **United States Design Patent** (10) **Patent No.:** **US D824,969 S**
Alfaro et al. (45) **Date of Patent:** **** Aug. 7, 2018**

(54) **CERAMIC BONDING TOOL WITH TEXTURED TIP**

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(71) Applicant: **COORSTEK, INC.**, Golden, CO (US)

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(72) Inventors: **Cesar Alfaro**, Lewisville, TX (US); **Russell Bell**, Ventura, CA (US); **Anne Cenedella**, Evergreen, CO (US); **Steve Govorchin**, Superior, CO (US); **Mark S. Greenwell**, Ventura, CA (US); **Brian Seegmiller**, Arvada, CO (US); **Matthew Simpson**, Evergreen, CO (US)

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(73) Assignee: **CoorsTek, Inc.**, Golden, CO (US)

Primary Examiner — Patricia A Palasik
(74) *Attorney, Agent, or Firm* — Faegre Baker Daniels LLP

(**) Term: **15 Years**

(57) **CLAIM**

(21) Appl. No.: **29/612,580**

The ornamental design for a ceramic bonding tool with textured tip, as shown and described.

(22) Filed: **Aug. 2, 2017**

DESCRIPTION

Related U.S. Application Data

(62) Division of application No. 29/516,521, filed on Feb. 3, 2015, now Pat. No. Des. 797,826.

(51) **LOC (11) Cl.** **15-09**

(52) **U.S. Cl.**
USPC **D15/144**

(58) **Field of Classification Search**
USPC D8/14, 14.1, 29, 29.1, 29.2, 30;
D15/122, 138, 144, 144.1, 144.2;
(Continued)

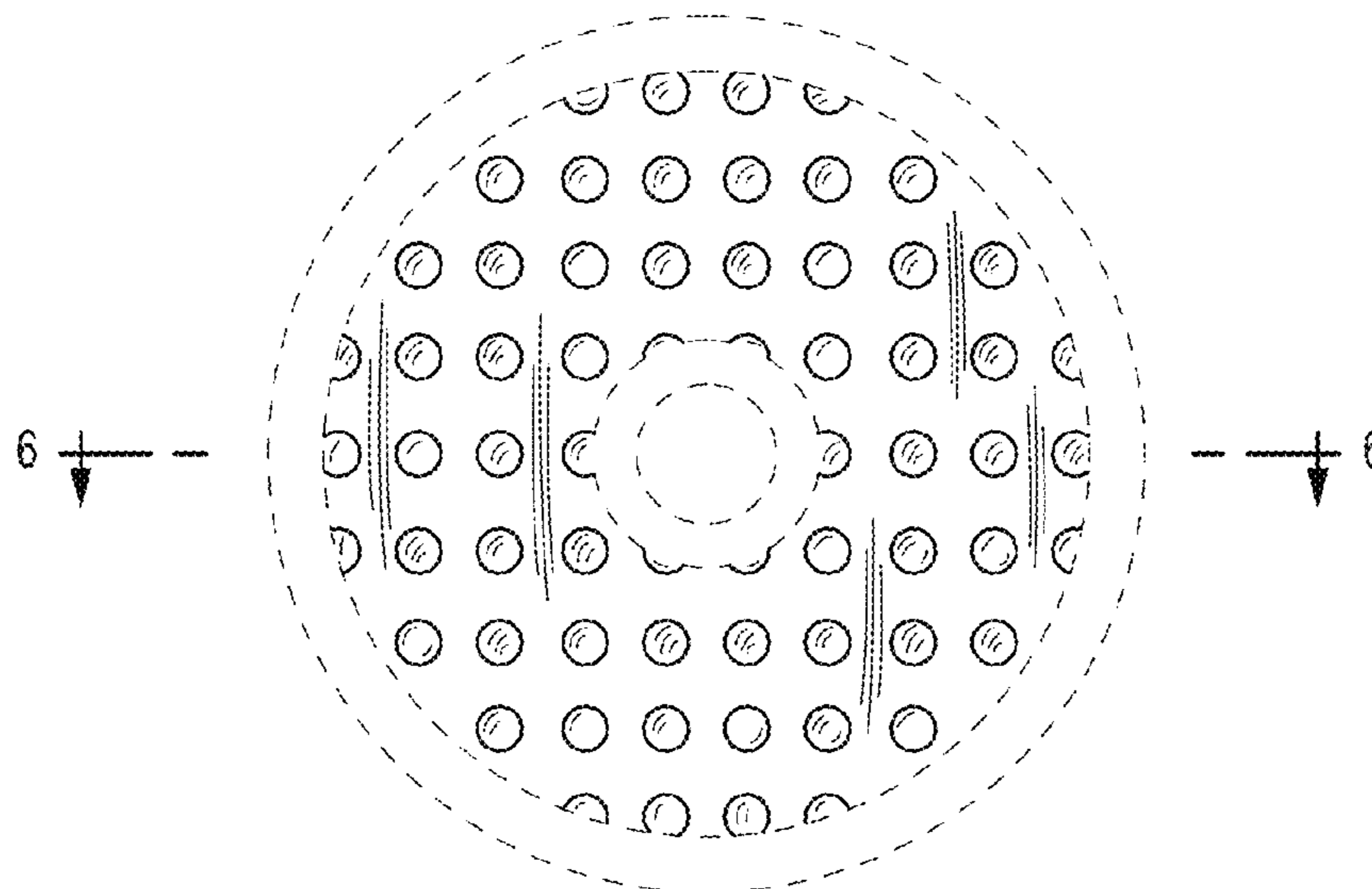
FIG. 1 depicts a perspective view of a ceramic bonding tool with textured tip.
FIG. 2 depicts a side elevation view of the ceramic bonding tool with textured tip of FIG. 1.
FIG. 3 depicts a top plan view of the ceramic bonding tool with textured tip of FIG. 1.
FIG. 4 depicts a bottom plan view of the ceramic bonding tool with textured tip of FIG. 1.
FIG. 5 depicts a detailed bottom plan view of the ceramic bonding tool with textured tip shown in FIG. 4; and,
FIG. 6 depicts a detailed side cross-section view of the ceramic bonding tool with textured tip, the cross-section taken along cross-section indicator line 6-6 of FIG. 5.
The broken lines in the drawings illustrate environmental structure on the article and form no part of the claimed design.

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1 Claim, 3 Drawing Sheets



(58) **Field of Classification Search**
 USPC 219/121.39, 121.46, 121.45, 121.5,
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 CPC .. B23K 20/004; B23K 20/005; B23K 20/106;
 H01L 24/85
 See application file for complete search history.

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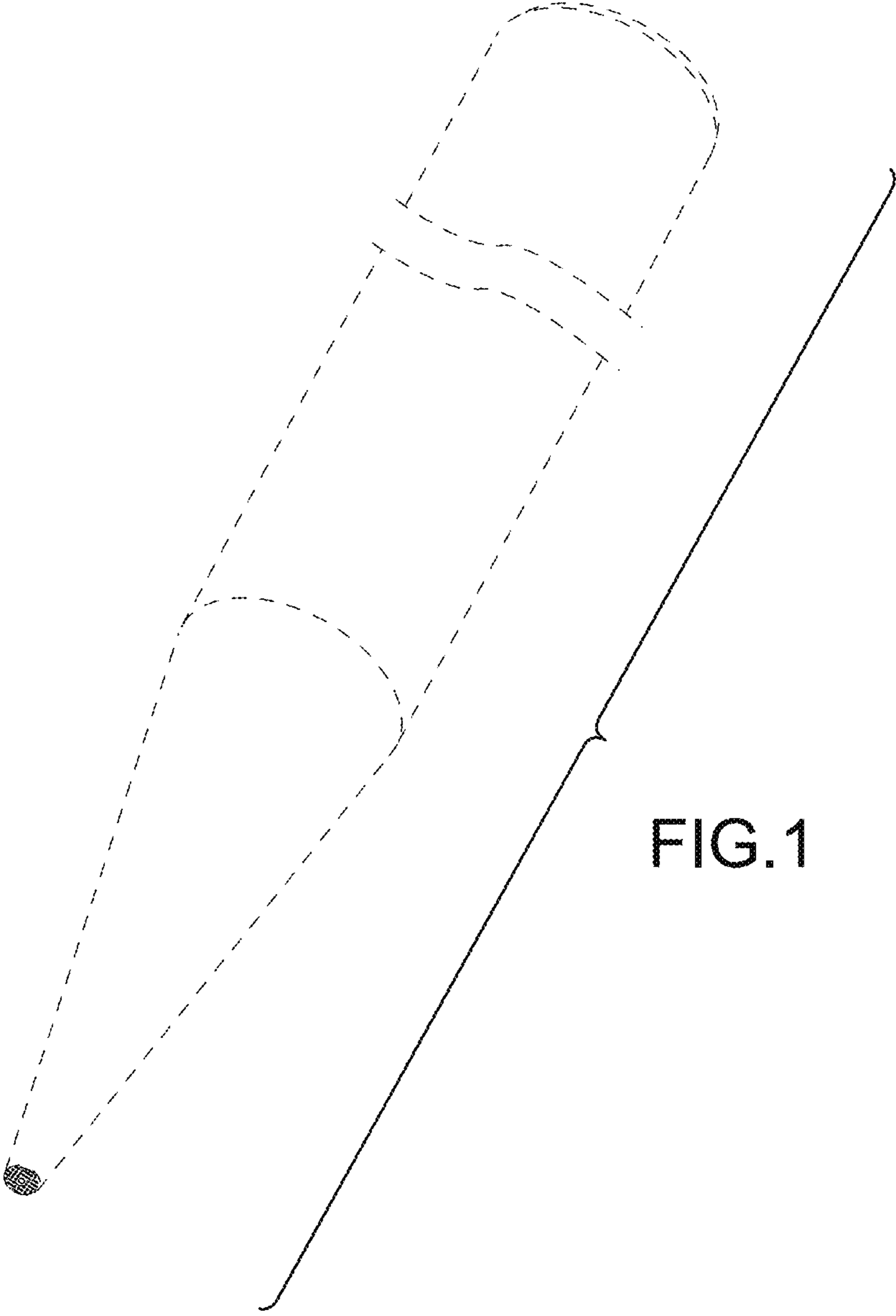


FIG. 1

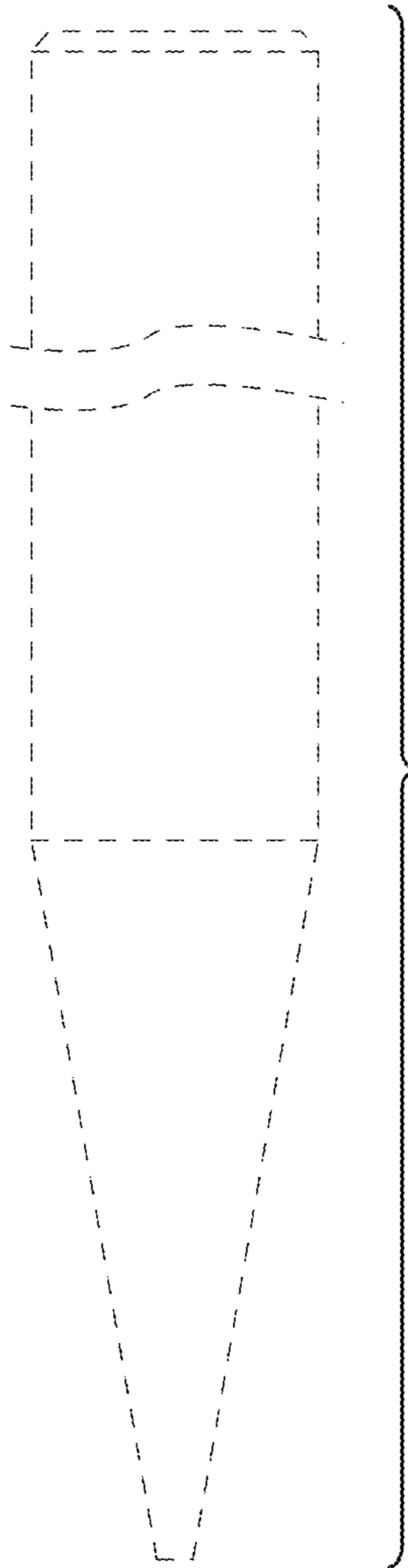


FIG. 2

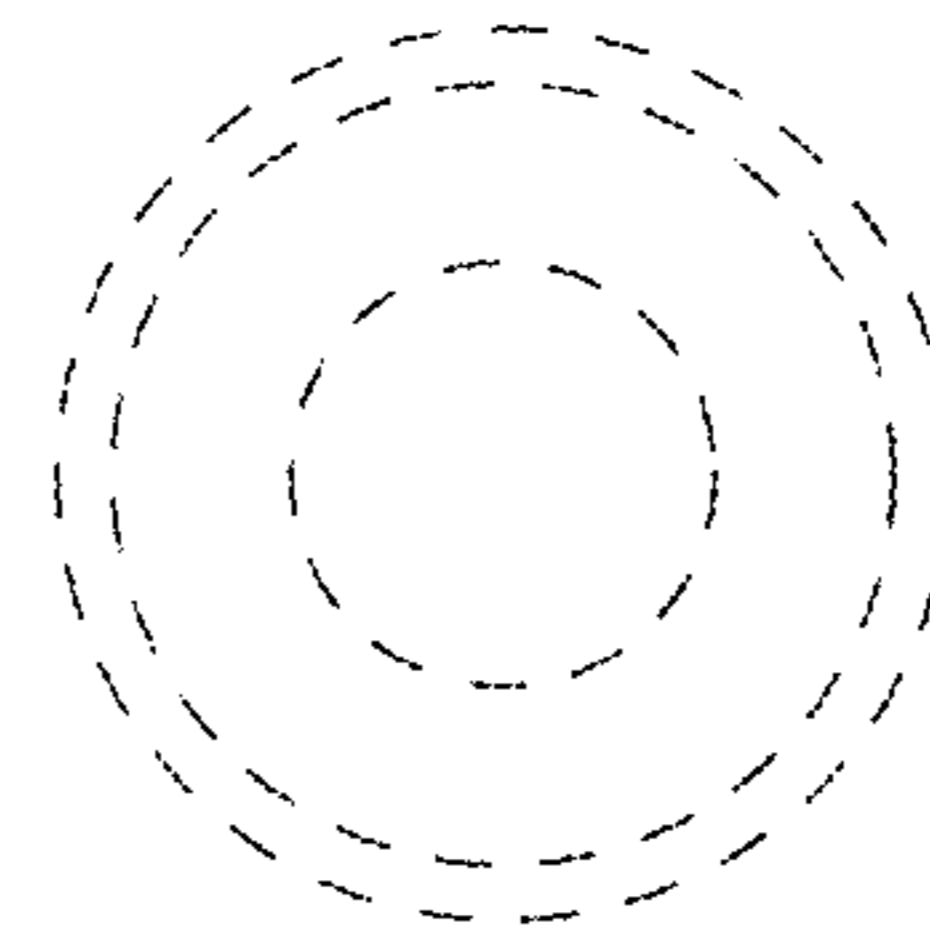


FIG. 3

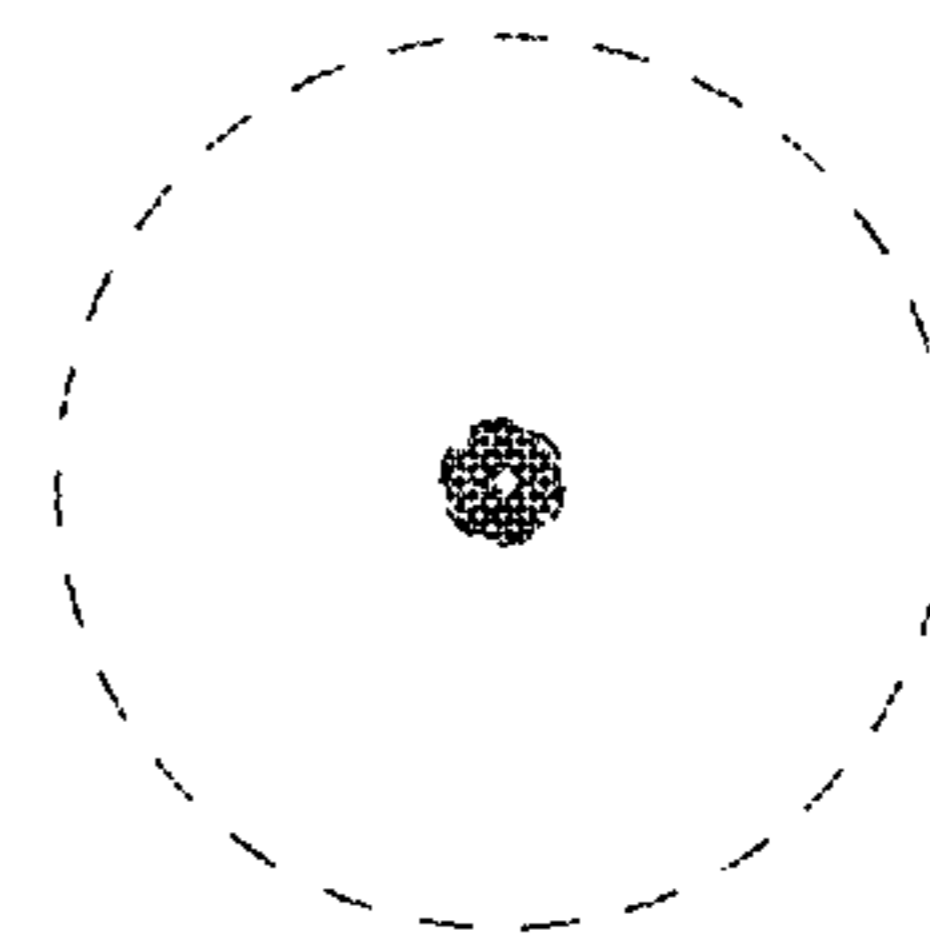


FIG. 4

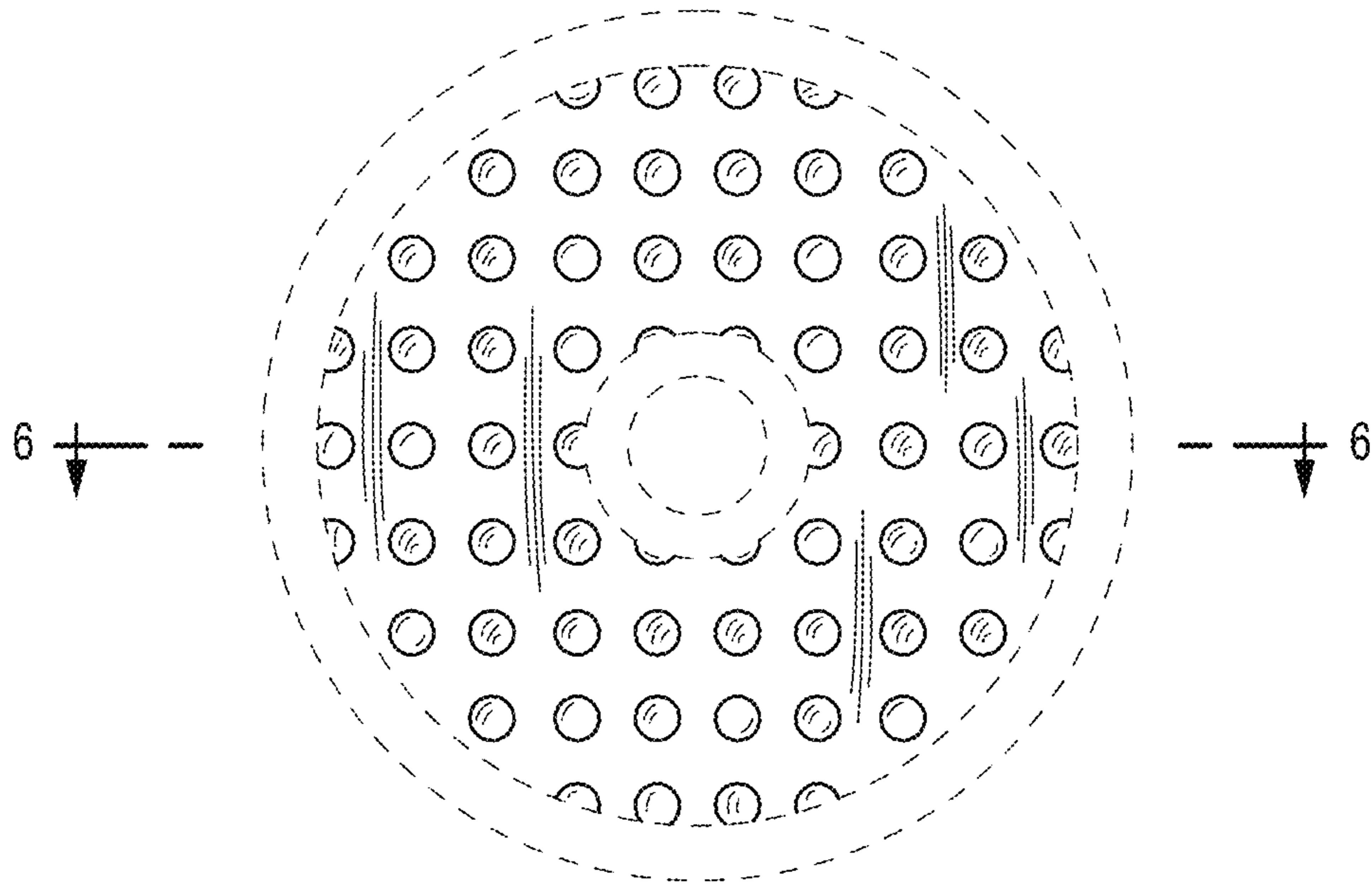


FIG. 5

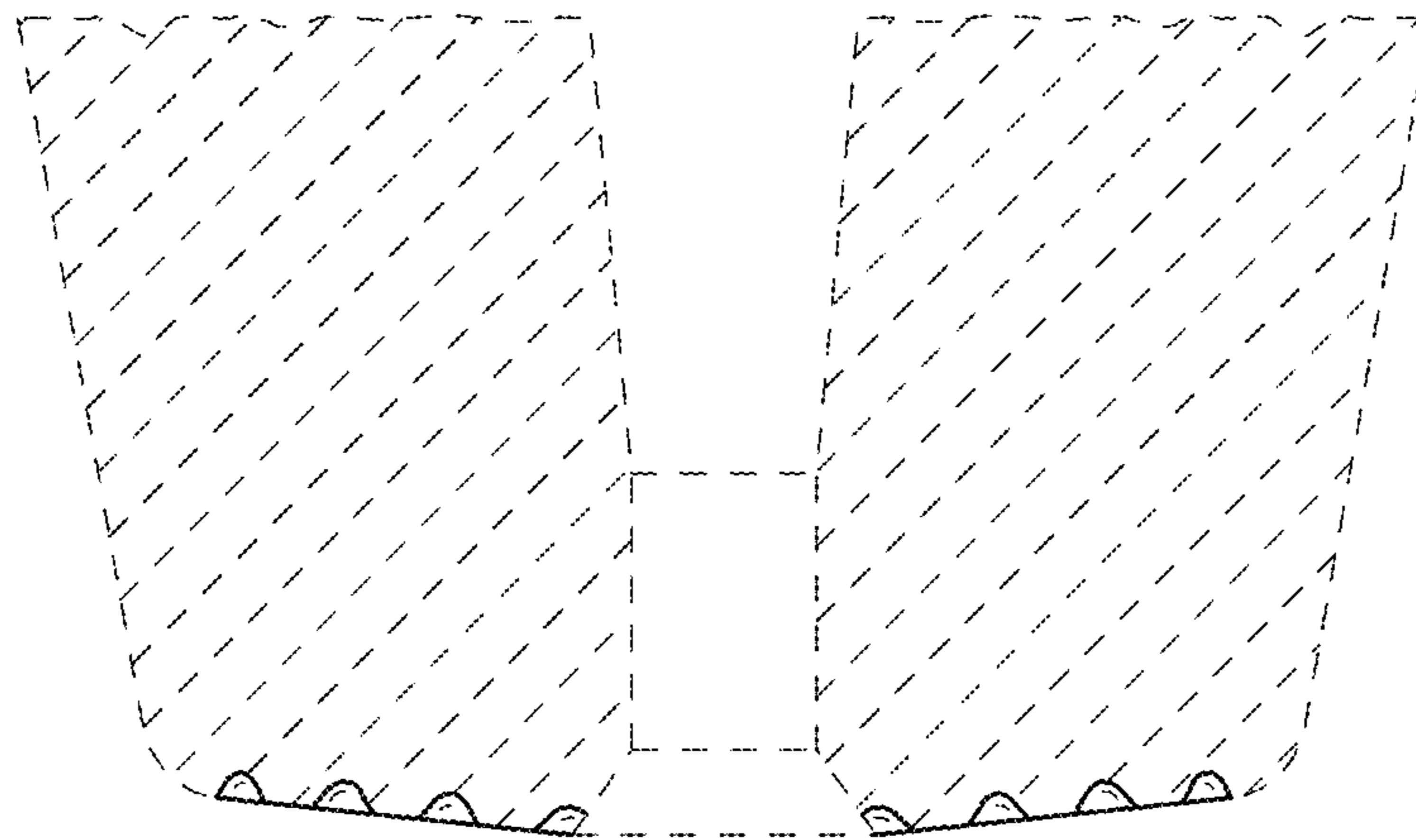


FIG. 6